




# Power MOSFETS


## DATASHEET


---


**LM1C070NAK8A**

N-Channel  
Enhancement Mode MOSFET

 Leadpower-semiconductor Corp., Ltd

 [sales@leadpower-semi.com](mailto:sales@leadpower-semi.com)

 (03) 6577339 FAX : (03) 6577229

 [www.leadpower-semi.com](http://www.leadpower-semi.com)

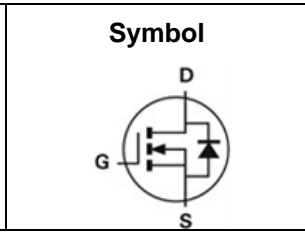
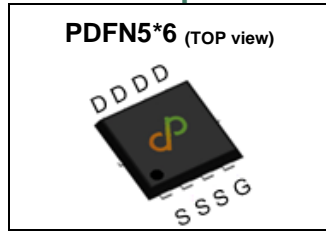


Quality Management Systems

ISO 9001:2015 Certificate

## N-Channel Enhancement Mode MOSFET

### Pin Description



### Product Summary

Symbol	N-Channel	Unit
$V_{DSS}$	120	V
$R_{DS(ON)-Max}$	7	m $\Omega$
ID	103	A

### Feature

- High Speed Power Switching , Logic Level
- Reliable and Rugged
- ROHS Compliant & Halogen-Free
- 100% UIS and Rg Tested

### Applications

- Hard Switching and High Speed Circuit
- DC/DC in Telecoms and Industrial

### Ordering Information

Orderable Part Number	Package Type	Form	Shipping	Marking
LM1C070NAK8A	PDFN5*6	Tape & Reel	5000 / Tape & Reel	1C070 □□□□□□

### Absolute Maximum Ratings (T<sub>J</sub>=25°C Unless Otherwise Noted)

Symbol	Parameter	N-Channel	Unit	
$V_{DSS}$	Drain-Source Voltage	120	V	
$V_{GSS}$	Gate-Source Voltage	±20		
$T_J$	Maximum Junction Temperature	150	°C	
$T_{STG}$	Storage Temperature Range	-55 to 150	°C	
$I_{DM}^{①}$	Pulse Drain Current Tested	$T_C=25^\circ C$	142	A
$I_D$	Continuous Drain Current	$T_C=25^\circ C$	103	A
		$T_C=100^\circ C$	65	
$P_D$	Maximum Power Dissipation	$T_C=25^\circ C$	125	W
		$T_C=100^\circ C$	50	
$I_{AS}^{②}$	Avalanche Current, Single pulse	L=0.1mH	48	A
$E_{AS}^{③}$	Avalanche Energy, Single pulse	L=0.1mH	115	mJ

### Thermal Characteristics

Symbol	Parameter	Rating	Unit	
$R_{\theta JC}$	Thermal Resistance-Junction to Case	Steady State	1	°C/W
$R_{\theta JA}^{③}$	Thermal Resistance-Junction to Ambient	Steady State	48	°C/W

Note ① : Max. current is limited by bonding wire

Note ② : UIS tested and pulse width are limited by maximum junction temperature 150°C

Note ③ : Surface Mounted on 1in<sup>2</sup> FR-4 board with 1oz.

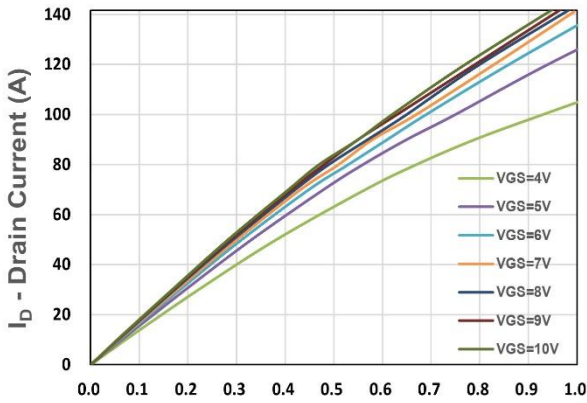
## N-Channel Electrical Characteristics (T<sub>J</sub>=25°C Unless Otherwise Noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
<b>Static Electrical Characteristics</b>						
<b>BV<sub>DSS</sub></b>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>DS</sub> =250uA	120	-	-	V
<b>I<sub>DSS</sub></b>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =96V, V <sub>GS</sub> =0V	-	-	1	uA
<b>V<sub>GS(th)</sub></b>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>DS</sub> =250uA	1	2	3	V
<b>I<sub>GSS</sub></b>	Gate Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	-	-	±100	nA
<b>R<sub>DS(ON)</sub></b> <sup>④</sup>	Drain-Source On-state Resistance	V <sub>GS</sub> =10V, I <sub>DS</sub> =20A	-	5.8	7	mΩ
		V <sub>GS</sub> =4.5V, I <sub>DS</sub> =20A	-	7.5	10	
<b>g<sub>fs</sub></b>	Forward Transconductance	V <sub>DS</sub> =5V, I <sub>DS</sub> =10A	-	46.6	-	S
<b>Dynamic Characteristics</b> <sup>®</sup>						
<b>R<sub>G</sub></b>	Gate Resistance	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, Freq.=1MHz	-	2.3	-	Ω
<b>C<sub>iss</sub></b>	Input Capacitance	V <sub>GS</sub> =0V, V <sub>DS</sub> =60V, Freq.=1MHz	-	4046	-	pF
<b>C<sub>oss</sub></b>	Output Capacitance		-	427	-	
<b>C<sub>rss</sub></b>	Reverse Transfer Capacitance		-	46	-	
<b>t<sub>d(ON)</sub></b>	Turn-on Delay Time	V <sub>GS</sub> =10V, V <sub>DS</sub> =60V, I <sub>D</sub> =1A, R <sub>GEN</sub> =6Ω	-	11	-	nS
<b>t<sub>r</sub></b>	Turn-on Rise Time		-	17.5	-	
<b>t<sub>d(OFF)</sub></b>	Turn-off Delay Time		-	56.6	-	
<b>t<sub>f</sub></b>	Turn-off Fall Time		-	96.9	-	
<b>Q<sub>g</sub></b>	Total Gate Charge	V <sub>GS</sub> =4.5V, V <sub>DS</sub> =60V I <sub>D</sub> =20A	-	25.7	-	nC
<b>Q<sub>g</sub></b>	Total Gate Charge	V <sub>GS</sub> =10V, V <sub>DS</sub> =60V, I <sub>D</sub> =20A	-	54.7	-	
<b>Q<sub>gs</sub></b>	Gate-Source Charge		-	14.4	-	
<b>Q<sub>gd</sub></b>	Gate-Drain Charge		-	6.2	-	
<b>Source-Drain Characteristics</b>						
<b>V<sub>SD</sub></b> <sup>④</sup>	Diode Forward Voltage	I <sub>SD</sub> =10A, V <sub>GS</sub> =0V	-	0.8	1.1	V
<b>t<sub>rr</sub></b>	Reverse Recovery Time	I <sub>F</sub> =10A, V <sub>R</sub> =50V	-	64.8	-	nS
<b>Q<sub>rr</sub></b>	Reverse Recovery Charge	dI <sub>F</sub> /dt=100A/μs	-	100	-	nC

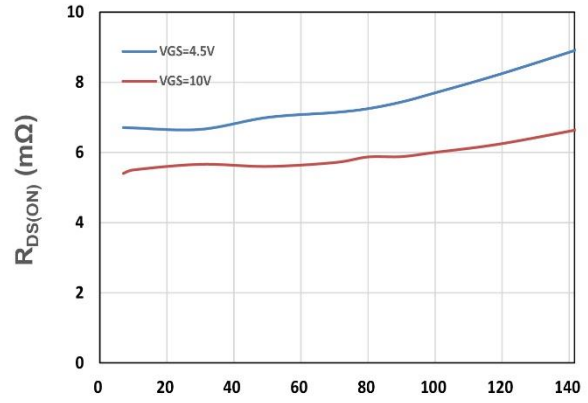
Note ④ : Pulse test (pulse width≤300us, duty cycle≤2%).

Note ⑤ : Guaranteed by design, not subject to production testing.

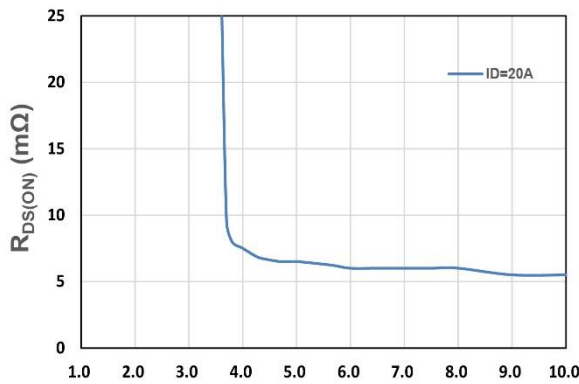
## N-Channel Typical Characteristics



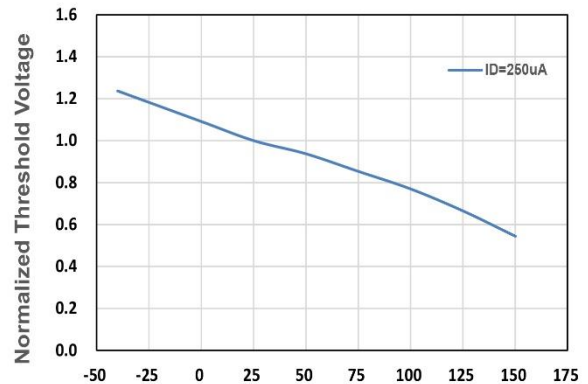
$V_{DS}$  - Drain - Source Voltage (V)  
Figure 1. Output Characteristics



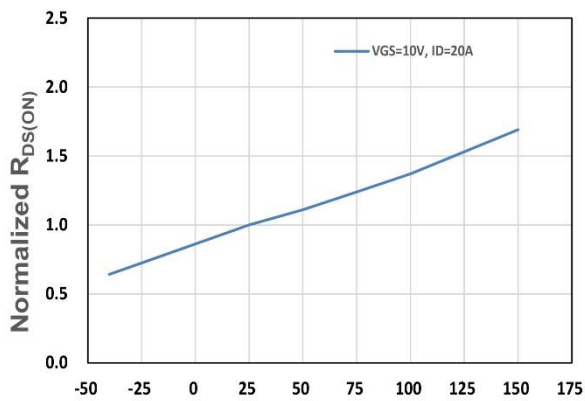
$I_D$ - Drain Current (A)  
Figure 2. On-Resistance vs. ID



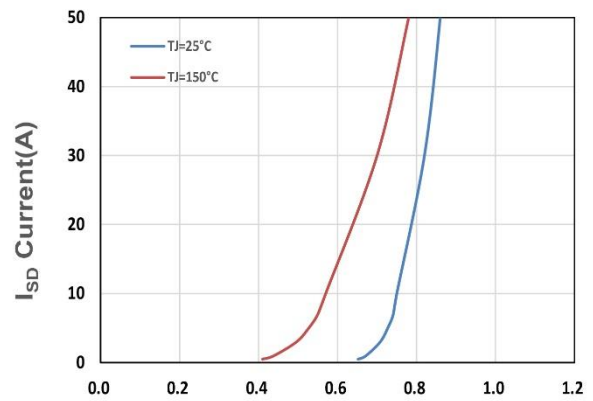
$V_{GS}$  - Gate - Source Voltage (V)  
Figure 3. On-Resistance vs. VGS



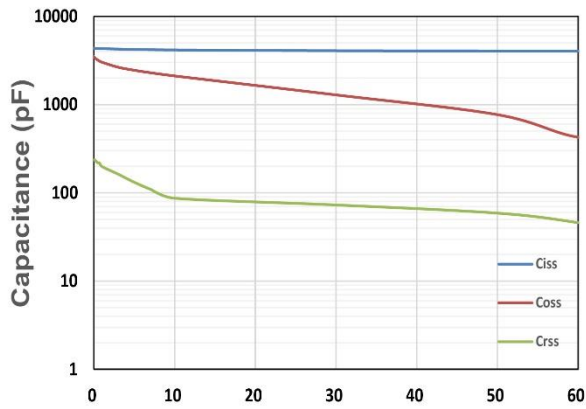
$T_j$ , Junction Temperature(°C)  
Figure 4. Gate Threshold Voltage



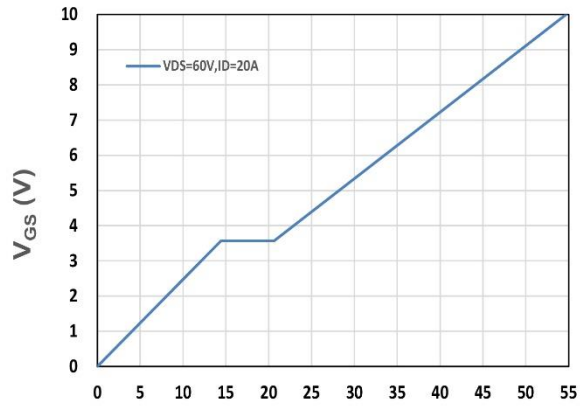
$T_j$ , Junction Temperature(°C)  
Figure 5. Drain-Source On Resistance



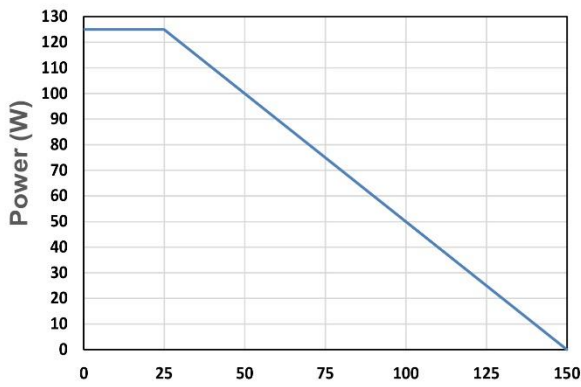
$V_{SD}$ , Source-Drain Voltage(V)  
Figure 6. Source-Drain Diode Forward



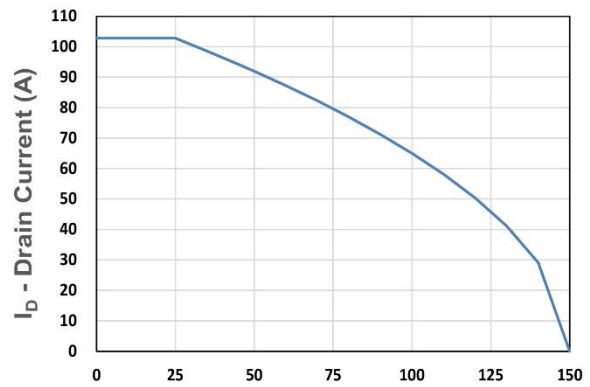
$V_{DS}$  - Drain - Source Voltage (V)  
Figure 7. Capacitance



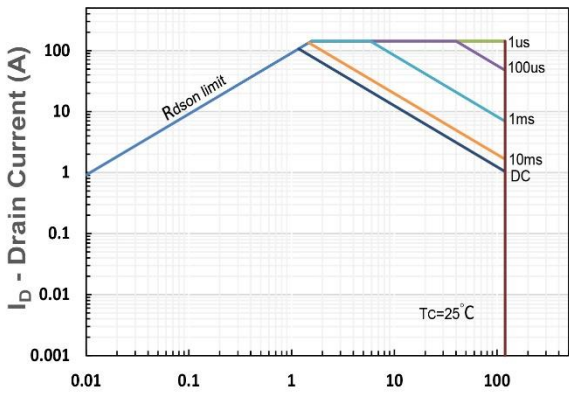
$Q_g$ , Total Gate Charge (nC)  
Figure 8. Gate Charge Characteristics



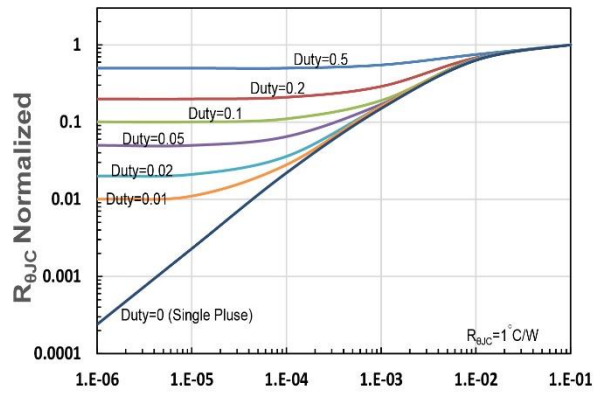
$T_c$  - Case Temperature (°C)  
Figure 9. Power Dissipation



$T_c$  - Case Temperature (°C)  
Figure 10. Drain Current



$V_{DS}$  - Drain-Source Voltage (V)  
Figure 11. Safe Operating Area



$t_1$ , Square Wave Pulse Duration(s)  
Figure 12.  $R_{\theta JC}$  Transient Thermal Impedance